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PATENT NUMBER and  
ISSUE DATE

## U.S. UTILITY Patent Application

APPL NUM 10019056	FILING DATE 04/22/2002	CLASS 257	SUBCLASS	GAU 2811	EXAMINER T. TRAV
<b>**APPLICANTS:</b> Demizu Kiyoshi; Kato Tadahiro; Netsu Shigeyoshi;					
<b>**CONTINUING DATA VERIFIED:</b> THIS APPLICATION IS A 371 OF PCT/JP01/03635 04/26/2001  YES TT					
<b>** FOREIGN APPLICATIONS VERIFIED:</b> JAPAN 2000-128502 04/27/2000  YES TT					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO			
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		155/50674			
Verified and Acknowledged Examiners's initials					
TITLE : Semiconductor wafer and device for semiconductor device manufacturing process <small>U.S. DEPT. OF COMM./PAT. &amp; TM.-PTO-436L (Rev. 12-94)</small>					

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<b>NOTICE OF ALLOWANCE MAILED</b>		Assistant Examiner		<b>CLAIMS ALLOWED</b>	
				Total Claims	Print Claim for O.G.
<b>ISSUE FEE</b>		Primary Examiner		<b>DRAWING</b>	
Amount Due	Date Paid			Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		<b>PREPARED FOR ISSUE</b>		Application Examiner	
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